SPI5012 SERIES

1. PART NO. EXPRESSION :

SPI	5012	-1R() N Z F
(a)	(b)	(C)	(d)(e)(f)

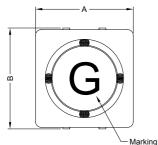
(a) Series code	

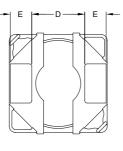
(b) Dimension code

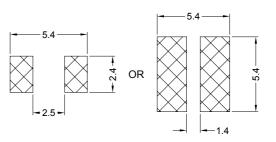
- (c) Inductance code : 1R0 = 1.0uH
- (d) Tolerance code : M = ±20%, N = ±30%(e) Z : Standard part
- (f) F : RoHS Compliant

Unit:m/m

2. CONFIGURATION & DIMENSIONS :







Recommended PCB Pattern

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А	В	С	D	E	F	G
5.0±0.2	5.0±0.3	1.2 Max.	2.7 Тур	1.16 Тур	2.0 Тур	1.5 Тур

3. MATERIALS :

- (a) Core : Ferrite
- (b) Wire : Polyurethane Enamelled Copper Wire
- (c) Terminal Clip : C5191
- (d) Adhesive : Epoxy
- (e) Ink : 70000-00101



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10.02.2010

SPI5012 SERIES

4. GENERAL SPECIFICATION :

a) IDC1 : Based on inductance change $(\Delta L/Lo: \leq 30\%)$ @ ambient temp. 25°C

b) IDC2 : Based on temperature rise $(\Delta T: 40^{\circ}C \text{ Typ.})$

c) Rated Current : IDC1 or IDC2, whichever value is lower

d) Storage temp. : -40°C to +105°C

e) Operating temp. : -40°C to +105°C (include self temp. rise)

f) Resistance to solder heat : 260°C 10secs

5. ELECTRICAL CHARACTERISTICS :

Part No.	Inductance (uH)	Test Frequency (Hz)	RDC (mΩ) ±20%	IDC1 (A)	IDC2 (A)	Marking
SPI5012-1R0NZF	1.0±30%	0.1V/100K	45	2.50	2.30	А
SPI5012-1R5NZF	1.5±30%	0.1V/100K	52	2.10	2.00	С
SPI5012-2R2NZF	2.2±30%	0.1V/100K	71	1.70	1.70	E
SPI5012-3R3NZF	3.3±30%	0.1V/100K	80	1.40	1.50	G
SPI5012-4R7MZF	4.7±20%	0.1V/100K	120	1.20	1.30	I
SPI5012-6R8MZF	6.8±20%	0.1V/100K	150	1.00	1.10	к
SPI5012-100MZF	10±20%	0.1V/100K	220	0.75	1.00	М
SPI5012-150MZF	15±20%	0.1V/100K	320	0.65	0.85	0
SPI5012-220MZF	22±20%	0.1V/100K	430	0.53	0.70	Q
SPI5012-330MZF	33±20%	0.1V/100K	680	0.42	0.50	S
SPI5012-470MZF	47±20%	0.1V/100K	1050	0.30	0.38	U



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10.02.2010

SPI5012 SERIES

6. RELIABILITY & TEST CONDITION :

ITEM	PERFORMANCE	TEST CONDITION	
Mechanical			
Substrate bending	ΔL/Lo≦±10% There shall be no mechanical damage or electrical damage.	The sample shall be soldered onto the printed circuit board in figure 1 and a load applied until the figure in the arrow direction is made approximately 3mm.(keep time 30 secs 100 - 50 - 004.5 100 -	
		PRESSURE ROD figure-1	
Vibration	ΔL/Lo≦±10% There shall be no mechanical damage.	The sample shall be soldered onto the printed circuit board and when a vibration having an amplitude of 1.52mm and a frequency of from 10 to 55Hz/1 minute repeated should be applied to the 3 directions (X,Y,Z) for 2 hours each. (A total of 6 hours)	
Solderability	New solder More than 90%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated over the whole of the sample before hard, the sample shall then be preheated for about 2 minutes in a temperature of $130 \sim 150^{\circ}$ C and after it has been immersed to a depth 0.5mm below for 3 ± 0.2 seconds fully in molten solder M705 with a temperature of $245\pm5^{\circ}$ C. More than 90% of the electrode sections shall be cowered with new solder smoothly when the sample is taken out of the solder bath.	
Resistance to Soldering heat (reflow soldering)	There shall be no damage or problems.	Soldering (Peak temperature 260±3°C 10sec)	



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10.02.2010

SPI5012 SERIES

6. RELIABILITY & TEST CONDITION :

ITEM	PERFORMANCE	TEST CONDITION			
Electrical Characteristics Test					
Dielectric withstand voltage	There shall be no damage or problems.	AC 100V voltage shall be applied for 1 minute across the top surface and the terminal of this sample			
Temperature characteristics	ΔL/L20°C≦±10% 0~2000 ppm/°C	The test shall be performed after the sample has stabilized in an ambient temperature of -20 to +85°C, and the value calculated based on the value applicable in a normal temperature and normal humidity shall be $\Delta L/L20°C \leq 10\%$.			
High temperature storage	ΔL/Lo≦±10% There shall be no mechanical damage.	The sample shall be left for 96±4 hours in an atmosphere with a temperature of 85±2°C and a normal humidity. Upon completion of the measurement shall be made after the sample has been left in a normal temperature and normal humidity for 1 hour.			
Low temperature storage	ΔL/Lo≦±10% There shall be no mechanical damage.	The sample shall be left for 96±4 hours in an atmosphere with a temperature of -25±3°C. Upon completion of the test, the measurement shall be made after the sample has been left in a normal temperature and normal humidity for 1 hour.			
Change of temperature	ΔL/Lo≦±10% There shall be no other damage of problems	The sample shall be subject to 5 continuous cycles, such shown in the table 2 below and then it shall be subjected standard atmospheric conditions for 1 hour, after which measurement shall be made.			
		TemperatureDuration-25±3°C30 min.1(Thermostat No.1)			
		Standard 5 sec. or less 2 atmospheric No.1→No.2			
		85±2°C3(Thermostat No.2)30 min.			
		4 Standard 5 sec. or less atmospheric No.2→No.1			
Moisture storage	ΔL/Lo≦±10% There shall be no mechanical damage.	The sample shall be left for 96±4 hours in a temperature of 40±2°C and a humidity(RH) of 90~95%. Upon completion of the test, the measurement shall be made after the sample has been left in a normal temperature and normal humidity more than 1 hour.			



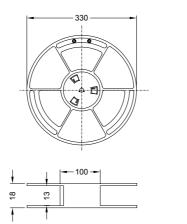
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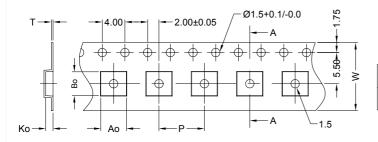
7. PACKAGING INFORMATION :

7-1. Reel Dimension (mm)



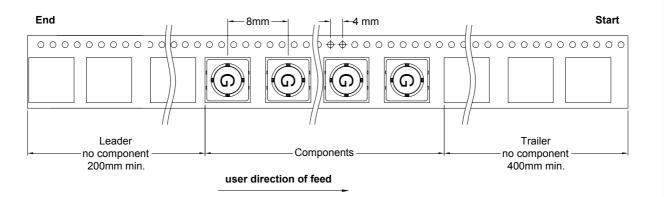


7-2 CARRIER TAPE DIMENSIONS (mm)



Ao	Во	Ko	W	Р	Т
5.5mm	5.2mm	1.55mm	12mm	8.0mm	0.3mm

7-3 TAPING DIMENSIONS (mm)



7-4 QUANTITY

3000pcs/Reel

The products are packaged so that no damage will be sustained.



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